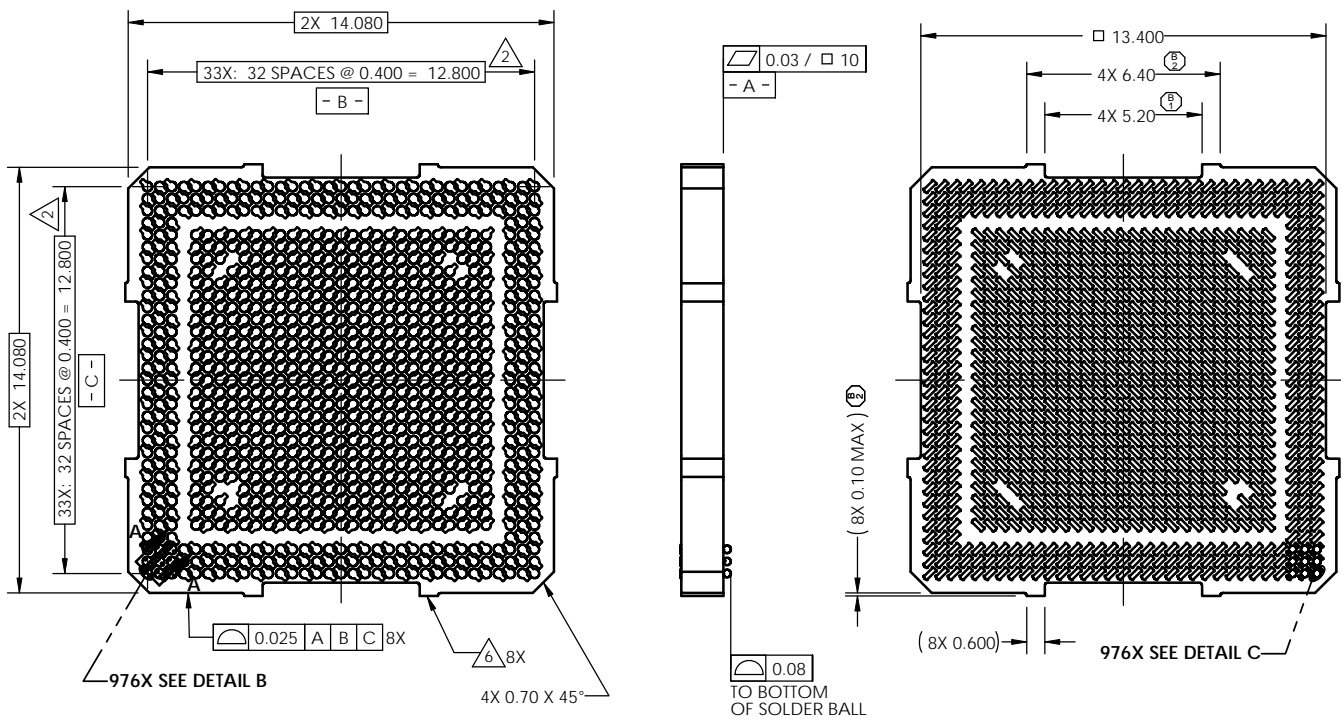
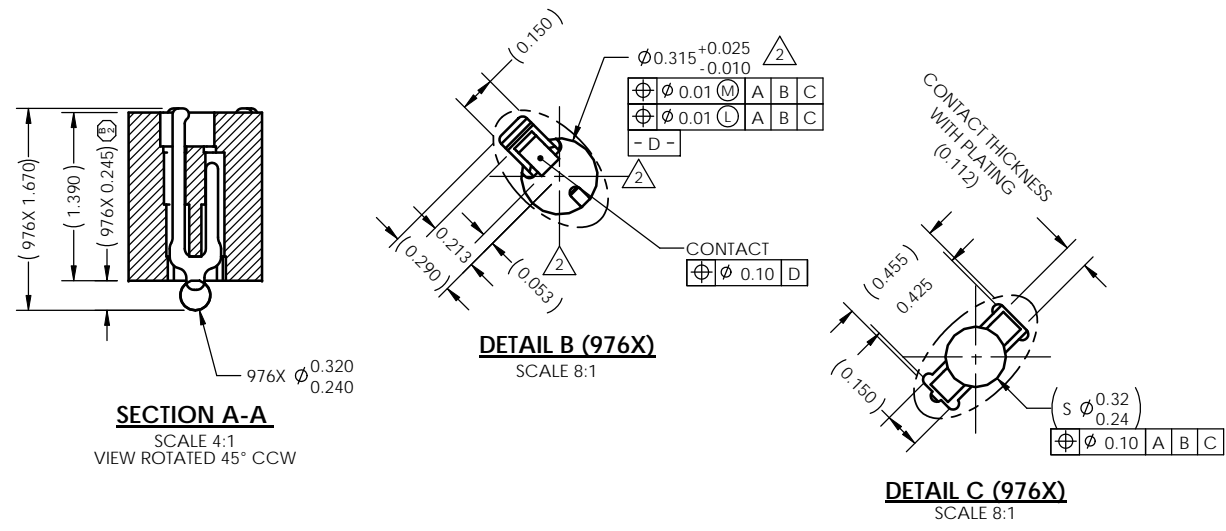


REV	ECO	BY	DESCRIPTION	APV	DATE
A	30076	SK	Initial Design	MP	01/22/10
B	30201	CW	1) Was 8.00 2) Added dim. 3) was 15.75	MP	03/24/10



- Notes:
- Reference Cascade Microtech specification 103862-0004 for solder attachment.
  - Dimension locates center of contact/ slot.
  - Reference Cascade Microtech specification 103863-0001 for application notes.
  - Socket designed for Qualcomm package as defined on outline drawing (POD) CV90-VP995-1 Rev D.
  - Datums B and C are determined by  $\phi 0.315$  openings on corner slots.
  - Tooling marks permitted. Maximum 0.10 protrusion (shown).

Parts List				
Item	Qty	Part Number	Description	
-	-	107140-0008	SCKT, 976G4014-0.40	
-	-	103864-0004	PRESS, DEVICE INSERT, GRYP 14X14 (SOLD SEPARATELY)	
-	-	105900-0004	EXTRACTION TOOL, 4 X 53 (SOLD SEPARATELY)	
1	1	107141-0008	CS, 976G4014-0.40 W/SOLDER BALLS	
1.1	1	107143-0008	HSG, 976G4014-0.40	
1.2	976	104468-0014	CONTACT, G40, HALF, $\phi 0.25$ , TIN, 0.1016	



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS DIMS APPLY AFTER PLATING TOLERANCES UNLESS OTHERWISE NOTED:

ANGLES:  $\pm 1^\circ$

DECIMALS: XX  $\pm 0.25$ , XXX  $\pm 0.10$ , XXXX  $\pm 0.050$

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CAD GENERATED DRAWING DO NOT MANUALLY UPDATE

7115 NORTHLAND TERRACE SUITE 400 BROOKLYN PARK, MN 55428 (763) 509-0066

DRAWING APPROVALS

DESIGN: S. Klanderud	DATE: 01/22/10
APPROV: M. Peery	DATE: 01/22/10

THIRD ANGLE PROJECTION

LEGEND:

- NOTE CALLOUT
- REVISION CHANGE
- ITEM NUMBER

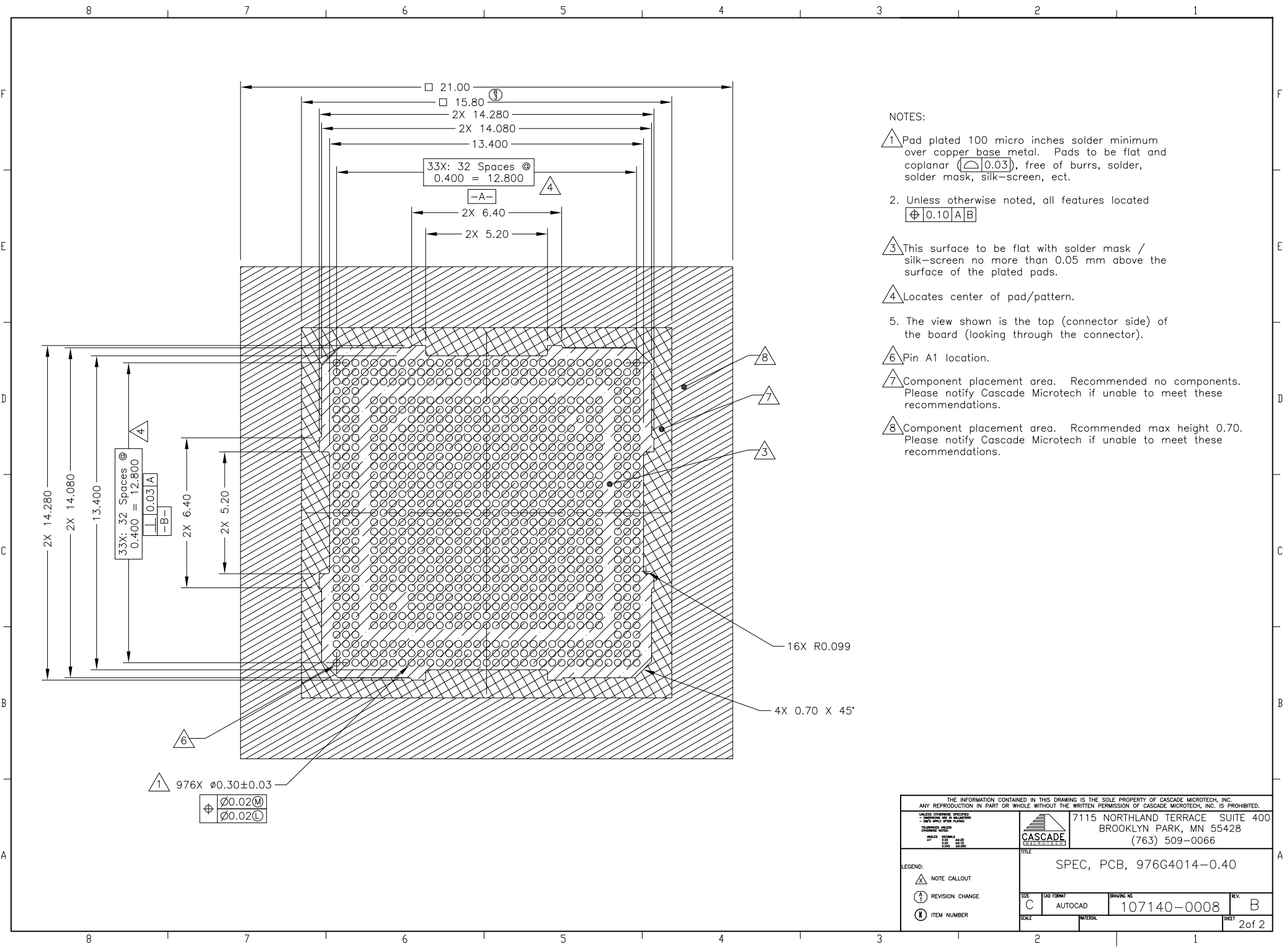
CASCADE MICROTECH

SCALE: C

107140-0008

SEE BOM

1 of 2



NOTES:

- 1. Pad plated 100 micro inches solder minimum over copper base metal. Pads to be flat and coplanar ( $\Delta 0.03$ ), free of burrs, solder, solder mask, silk-screen, ect.
- 2. Unless otherwise noted, all features located  $\Phi 0.10 | A | B$
- 3. This surface to be flat with solder mask / silk-screen no more than 0.05 mm above the surface of the plated pads.
- 4. Locates center of pad/pattern.
- 5. The view shown is the top (connector side) of the board (looking through the connector).
- 6. Pin A1 location.
- 7. Component placement area. Recommended no components. Please notify Cascade Microtech if unable to meet these recommendations.
- 8. Component placement area. Recommended max height 0.70. Please notify Cascade Microtech if unable to meet these recommendations.

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<small>UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS DIMENSIONS IN PARENTHESES ARE IN INCHES TOLERANCES UNLESS OTHERWISE NOTED: DIMENSIONS UNLESS OTHERWISE NOTED: FINISHES UNLESS OTHERWISE NOTED: ELECTROPLATING UNLESS OTHERWISE NOTED: SOLDER UNLESS OTHERWISE NOTED: SILK SCREEN UNLESS OTHERWISE NOTED</small>		7115 NORTHLAND TERRACE SUITE 400 BROOKLYN PARK, MN 55428 (763) 509-0066	
LEGEND: △ NOTE CALLOUT ⊕ REVISION CHANGE ① ITEM NUMBER		TITLE: SPEC, PCB, 976G4014-0.40	
SIZE: C CAD FORMAT: AUTOCAD SCALE:	DRAWING NO.: 107140-0008 MATERIAL:	REV: B SHEET: 2 of 2	